

	Typ e	Hits	Search Text	DBs	Time Stamp	Com ments	Error Defini tion	Error s
1	BR S	708 48	34/\$.ccls. 134/\$.ccls.	USPAT; EPO; JPO	2004/03 /01			0
2	BR S	344	(34/\$.ccls. 134/\$.ccls.) and (substrate wafer) and vacuum and cassette	USPAT; EPO; JPO	2004/03 /01 11:45			0
3	BR S	2	((34/\$.ccls. 134/\$.ccls.) and (substrate wafer) and vacuum and cassette) and (transfer with cassette) and (original with cassette with return)	USPAT; EPO; JPO	2004/03 /01 11:46			0
4	BR S	50	((34/\$.ccls. 134/\$.ccls.) and (substrate wafer) and vacuum and cassette) and (transfer with cassette) and (original with cassette)	USPAT; EPO; JPO	2004/03 /01 11:49			0
5	BR S	43	((34/\$.ccls. 134/\$.ccls.) and (substrate wafer) and vacuum and cassette) and (transfer with cassette) and (original with cassette) and dummy	USPAT; EPO; JPO	2004/03 /02 09:14			0
6	BR S	1	"4923584".PN.	USPAT	2004/03 /01			0
7	BR S	1	4923584.pn. and (plasma dummy)	USPAT; EPO; JPO	2004/03 /01			0

	Ty pe	Hits	Search Text	DBs	Time Stamp	Com ments	Error Defini tion	Error s
8	BR S	1	((34/\$.ccls. 134/\$.ccls.) and (substrate wafer) and vacuum and cassette) and (transfer with cassette) and (original with cassette) and dummy ) not kato	USPAT; EPO; JPO	2004/03 /02 09:15			0
9	BR S	43	((34/\$.ccls. 134/\$.ccls.) and (substrate wafer) and vacuum and cassette) and (transfer with cassette) and (original with cassette) and dummy	USPAT; EPO; JPO	2004/03 /02 09:16			0

	Typ e	Hits	Search Text	DBs	Time Stamp	Com ments	Error Defini tion	Error s
10	BR S	48	("3652444" "3981791" "4138306" "4226897" "4311427" "4313783" "4313815" "4318767" "4449885" "4457661" "4534314" "4563240" "4576698" "4634331" "4643629" "4705951" "4715764" "4824309" "4836733" "4836905" "4851101" "4895107" "4902934" "4903937" "4909695" "4911597" "4915564" "4917556" "4923584" "4924890" "4936329" "4951601"	USPAT	2004/03 /02 09:15			0

	Typ e	Hits	Search Text	DBs	Time Stamp	Com ments	Error Defini tion	Error s
11	BR S	1	(("3652444"   "3981791"   "4138306"   "4226897"   "4311427"   "4313783"   "4313815"   "4318767"   "4449885"   "4457661"   "4534314"   "4563240"   "4576698"   "4634331"   "4643629"   "4705951"   "4715764"   "4824309"   "4836733"   "4836905"   "4851101"   "4895107"   "4902934"   "4903937"   "4909695"   "4911597"   "4915564"   "4917556"   "4923584"   "4924890"   "4936329"   "4951601"	USPAT; EPO; JPO	2004/03 /02 09:16			0
12	BR S	10	(34/\$.ccls. 134/\$.ccls.) and ((substrate wafer) with dummy) and @py<1990	USPAT; EPO; JPO	2004/03 /02 09:28			0

	Typ	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
13	BR S	13	(34/\$.ccls. 134/\$.ccls.) and ((substrate wafer) with dummy) and @py<1993	USPAT; EPO; JPO	2004/03 /02 09:28			0
14	BR S	3	((34/\$.ccls. 134/\$.ccls.) and ((substrate wafer) with dummy) and @py<1993) not ((34/\$.ccls. 134/\$.ccls.) and ((substrate wafer) with dummy) and @py<1990)	USPAT; EPO; JPO	2004/03 /02 09:30			0
15	BR S	63	kato and (wafer substrate) and 34/\$.ccls.	USPAT; EPO; JPO	2004/03 /02 09:30			0
16	BR S	14	(kato and (wafer substrate) and 34/\$.ccls.) and kathryn	USPAT; EPO; JPO	2004/03 /02 09:31			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
17	BR S	49	("3652444" "3981791" "4138306" "4226897" "4311427" "4313783" "4313815" "4318767" "4449885" "4457661" "4534314" "4563240" "4576698" "4634331" "4643629" "4705951" "4715764" "4824309" "4836733" "4836905" "4851101" "4895107" "4902934" "4903937" "4909695" "4911597" "4915564" "4917556" "4923584" "4924890" "4936329" "4951601"	USPAT	2004/03 /02 09:31			0

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
18	BR S	3	((("3652444"   "3981791"   "4138306"   "4226897"   "4311427"   "4313783"   "4313815"   "4318767"   "4449885"   "4457661"   "4534314"   "4563240"   "4576698"   "4634331"   "4643629"   "4705951"   "4715764"   "4824309"   "4836733"   "4836905"   "4851101"   "4895107"   "4902934"   "4903937"   "4909695"   "4911597"   "4915564"   "4917556"   "4923584"   "4924890"   "4936329"   "4951601"	USPAT; EPO; JPO	2004/03 /02 09:31		0	

	Document ID	Issue Date	Title	Current OR	Current XRef	Inventor
1	US 5169407 A	1992 1208	Method of determining end of cleaning of semiconductor manufacturing apparatus	29/25.01	134/1; 204/19 2.33; 204/29 8.32; 216/59	Mase, Yasukazu et al.
2	US 5016663 A	1991 0521	Method of determining end of cleaning of semiconductor manufacturing apparatus	134/1	134/1.1; 204/19 2.33; 204/29 8.32; 216/59	Mase, Yasukazu et al.
3	US 4827867 A	1989 0509	Resist developing apparatus	118/64	118/32 0; 118/32 6; 118/52; 118/66 7; 134/10 5; 134/20 0; 134/90 2; 165/15 6; 165/16 9; 165/28 9; 165/64; 427/42 2	Takei, Toshitaka et al.



	Document ID	Issue Date	Title	Current OR	Current XRef	Inventor
4	US 4597989 A	1986 0701	Method of depositing silicon films with reduced structural defects	427/99	134/22.18; 134/37; 438/684; 438/758; 438/791; 438/905	Wonsowicz, Casimir J. et al.
5	US 4529474 A	1985 0716	Method of cleaning apparatus for forming deposited film	134/11	118/50.1; 118/620; 118/715; 134/1; 204/192.32; 204/298.33; 216/79; 427/585	Fujiyama, Yasutomo et al.
6	US 4512812 A	1985 0423	Method for reducing phosphorous contamination in a vacuum processing chamber	134/21	134/22.18; 134/30; 134/31; 134/42	Liebert, Reuel B. et al.
7	US 4412388 A	1983 1101	Method for drying semiconductor substrates	34/259	118/620; 219/690; 34/239	Takagi, Mikio et al.

	Document ID	Issue Date	Title	Current OR	Current XRef	Inventor
8	US 4201579 A	1980 0506	Method for removing photoresist by hydrogen plasma	430/323	134/1; 134/1.2; ; 204/19 2.32; 216/59; 257/E2 1.249; 257/E2 1.256; 315/11 1.21; 430/32 9; 430/49	Robinson, Frederick J. et al.
9	JP 03064916 A	1991 0320	WAFER WASHING METHOD		134/902	MIYAMOTO, YASUNORI
10	JP 63185032 A	1988 0730	ETCHING APPARATUS FOR SILICON SUBSTRATE		134/41	NONAKA, TSUTOMU
11	JP 62023116 A	1987 0131	WET SEMICONDUCTOR MANUFACTURING EQUIPMENT		34/58	EJIRI, IWAO
12	JP 59229822 A	1984 1224	ETCHING APPARATUS		134/1; 257/E2 1.215	NITTA, TAKEHISA
13	JP 58009325 A	1983 0119	SELF-ROTATIONAL WAFER DRYER		34/58; 34/108	OKUMURA, KATSUYA